

L Number	Hits	Search Text	DB	Time stamp
-	2	6133637.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/06 11:57
-	0	257/678,690,639,704	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:31
-	11564	(257/678-704).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:31
-	897010	((("257/678-704").CCLS.) and cover or lid or enclos\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:34
-	467	((("257/678-704").CCLS.) and 257/737	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:34
-	207098	((("257/678-704").CCLS.) and 257/737) and cover or lid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:35
-	9	((("257/678-704").CCLS.) and 257/737) and plastic adj body	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:50
-	1	((("257/678-704").CCLS.) and 257/737) and plastic adj body and base	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:49
-	0	((("257/678-704").CCLS.) and 257/737) and plastic adj body and air adj gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:52
-	22854	(257/678-737).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:53
-	5723	((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:54
-	6	((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$) and lead and expose\$ adj portion) and air adj gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:56
-	2	((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$) and lead and expose\$ adj portion) and plastic adj body	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:57
-	189	((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$) and lead and expose\$ adj portion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 16:27

-	1210	257/704	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:27
-	1	257/704 and bump and air adj gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:31
-	2	(257/704 and bump) and exposed adj portion same lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:32
-	118	257/704 and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:47
-	0	5311402.pn	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:47
-	3	5188280.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:57
-	3	5311402.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:57
-	1716	(glass near (lid cover substrate)) near3 plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 12:01
-	107	((glass near (lid cover substrate)) near3 plastic) and ((charge adj coupled adj device) ccd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 12:03
-	19	(glass near lid) near3 plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 07:53
-	1935	(glass near (lid cover substrate) near3 plastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 07:53
-	21	(glass near lid) near3 plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 08:08
-	9	semiconductor and (glass near body) near3 plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 08:08
-	590	((glass near (lid cover substrate) near3 plastic)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 08:30

-	127	((glass near (lid cover substrate) near3 plastic)) and semiconductor) and pack\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 08:52
-	4733	(257/666,678).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 08:53
-	3	((257/666,678).CCLS.) and ((glass near (lid cover substrate) near3 plastic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 08:56
-	16892	(257/660,666,678-704,734).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 08:57
-	7	((glass near (lid cover substrate) near3 plastic)) and ((257/660,666,678-704,734).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 08:57
-	4	((glass near (lid cover substrate) near3 plastic)) and ((257/660,666,678-704,734).CCLS.) not ((257/666,678).CCLS.) and ((glass near (lid cover substrate) near3 plastic)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:28
-	0	((die adj flag) (die adj pad)) with ('CuW' 'Cu/Mo/Cu')	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:30
-	286	((die adj flag) (die adj pad)) with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:32
-	3	((die adj flag) (die adj pad)) with (copper near3 tungsten)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:50
-	2	("5300791").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:50